

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Lu-Shih LIAO</td> <td>03/02/2012</td> </tr> <tr> <td>Ku-Chan CHIOU</td> <td>03/02/2012</td> </tr> </tbody> </table>		Name	Execution Date	Lu-Shih LIAO	03/02/2012	Ku-Chan CHIOU	03/02/2012
Name	Execution Date						
Lu-Shih LIAO	03/02/2012						
Ku-Chan CHIOU	03/02/2012						
RECEIVING PARTY DATA							
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Postal Code:	31040						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13458583</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13458583		
Property Type	Number						
Application Number:	13458583						
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NAME OF SUBMITTER:	Paul C. Lewis						
Total Attachments: 1 source=2012-04-30 Assignment 0941-2597PUS1#page1.tif							

OP \$40.00 13458583

**ASSIGNMENT**

WHEREAS, Lu-Shih LIAO and Kuo-Chan CHIOU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Low dielectric constant resin formulation, prepolymer, composition, and composite thereof  
 Title:

Filed: April 27, 2012 Serial No. 13/458,583

Executed on: March 2, 2012

WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

<b>Full name of sole or first inventor: Lu-Shih LIAO</b>	
Inventor's signature: <i>Lu-Shih Liao</i>	Date: <i>2012.3.2</i>

<b>Full name of second inventor: Kuo-Chan CHIOU</b>	
Inventor's signature: <i>Chiu</i>	Date: <i>2012.3.2</i>